Material Composition Declaration

EPC2070

Company Name	Efficient Power Conversion (EPC)	Issue Date:	11/2/2021
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.3074	90.1576	94.1393	901576
	Silicon oxide	7631-86-9	0.0089	0.6150		6150
	Silicon nitride	12033-89-5	0.0031	0.2165		2165
	Gallium nitride	25617-97-4	0.0063	0.4374		4374
	Aluminum	7429-90-5	0.0112	0.7746		7746
	Aluminum nitride	24304-00-5	0.0013	0.0929		929
	Titanium	7440-32-6	0.0002	0.0158		158
	Titanium nitride	25583-20-4	0.0107	0.7389		7389
	Copper	7440-50-8	0.0002	0.0129		129
	Tungsten	7440-33-7	0.0009	0.0605		605
	Polyimide		0.0147	1.0171		10171
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0066	0.0328	66
	Copper	7440-50-8	0.0004	0.0262		262
Solder Bump	Copper	7440-50-8	0.0589	4.0615	5.8279	40615
	Nickel	7440-02-0	0.0028	0.1954		1954
	Tin	7440-31-5	0.0224	1.5428		15428
	Silver	7440-22-4	0.0004	0.0283		283
Sum in total:			1.4501	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document w ithout notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the ele ctrical devices contained within the finished product.